

**BOILING PERFORMANCE ENHANCEMENT THROUGH
ENGINEERED SURFACE STRUCTURES AND JET FLOW FOR
HIGH HEAT FLUX APPLICATIONS**

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by

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DEPARTMENT OF MECHANICAL ENGINEERING

Submitted in fulfillment of the requirements of the degree of Doctor of Philosophy
to the



INDIAN INSTITUTE OF TECHNOLOGY DELHI

JULY 2025

Dedicated to My family and Teachers

Certificate

This is to certify that the thesis entitled **BOILING PERFORMANCE ENHANCEMENT THROUGH ENGINEERED SURFACE STRUCTURES AND JET FLOW FOR HIGH HEAT FLUX APPLICATIONS**, being submitted by **Mr. Rajesh Kumar** to the Indian Institute of Technology Delhi, for the award of the degree of **Doctor of Philosophy** in the Department of Mechanical Engineering is a bonafide record of the research work carried out by him under my guidance and supervision. To the best of my knowledge, the thesis has reached the requisite standard. We hereby declare that the content of the thesis, in full or in part, has not been submitted to any other Institute or University for the award of any degree or diploma.

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Rajesh Kumar

Abstract

Boiling is a highly efficient process of thermal energy transfer widely found across various engineering and industrial applications such as nuclear power reactors, water distillation, cryogenic fuel storage, steam power plant, refrigeration and air conditioning and thermal management of electronic devices. It uses latent heat of vaporization to transfer significantly large quantity of heat at a very low temperature difference. Consequently, it offers remarkably high heat transfer coefficients (HTC), making it a preferred mechanism for higher heat dissipation applications. However, the maximum heat flux in boiling is limited by the critical heat flux (CHF). After reaching the CHF, a vapor layer tends to develop over the heated surface, thereby HTC decreases significantly. Enhancement in boiling performance directly contributes energy efficiency, environmental sustainability and water resource utilization. Moreover, the ever-growing demand for compact, lightweight, and high-performance electronic devices calls for advanced thermal management solutions capable of handling higher heat dissipation rates to ensure reliable and efficient operation. Therefore, simple and inexpensive methods are required to further enhance both HTC and CHF to simultaneously increase the efficiency and operational range of systems. Various active and passive methods have been explored to improve boiling heat transfer. The current research work mainly focusses on the development of scalable, cost-effective and easy to implement enhancement technique for the pool boiling.

In this work, two new microchannel configurations, i.e., asymmetric dual V-groove microchannels (VM) and orthogonally intersecting asymmetric dual V-groove microchannels (OIVM) have been introduced to study enhancement in pool boiling. The heat transfer enhancement due to the modified surfaces is established by comparing the heat transfer rates from a reference plain surface. Moreover, to investigate the effect of reentrant channel geometry on heat transfer, two novel structured surfaces, namely trapezoidal reentrant microchannel (TRM) and segmented trapezoidal reentrant microchannel (STRM) are developed and boiling characteristics are experimentally investigated. A scalable porous copper coating is also developed to enhance heat transfer in pool boiling. The effect of surface characteristic parameters on the heat transfer performance is investigated. The submerged wall jet flow over a top-facing horizontal surface has also been investigated on the plain and the coated surfaces to improve the pool boiling heat transfer. In these studies, experiments have

been performed using deionized water under saturation temperature at one atmosphere pressure. The bubble dynamics and interface morphology at various heat flux levels have been captured using high-speed camera and discussed in detail. Finally, to explore the combined effect of surface structure and surface additive on the pool boiling performance, investigation has been carried out on the VM and OIVM surface using Triton X-100 surfactant solution.

It was observed that microchannels on the heated surface improve the heat transfer in pool boiling. The OIVM surface provides an increase of 5.3 times in the maximum HTC and 2.4 times in the CHF compared to the reference plain surface. Similarly, the VM surface provides an improvement of 2.2 times in HTC and 1.7 times in CHF compared to the plain surface. The increased heat transfer rate with the OIVM and VM surfaces can be ascribed to large area for heat exchange, increased bubble initiation sites, bubble motion promoted macroconvection and efficient rewetting mechanism. The TRM surfaces exhibit an enhancement factor of 2.08 to 2.91 times in the CHF and 2.33 to 3.96 times in the HTC compared to the plain surface. The top-performing STRM surface shows the CHF of 4555.2 kW/m² which is 290% higher than the plain surface CHF. This surface demonstrates a maximum HTC of 842.5 kW/m²K. The better heat transfer performance with the STRM surface compared to the TRM surface demonstrates that separated vapour release and liquid supply pathways, and better rewetting are the main reason for delayed CHF and higher HTC.

The coated surfaces provide better heat transfer performance than that of uncoated surface. The best-performing coated surface exhibits a HTC of 290.3 kW/m²K and a CHF of 2700.3 kW/m², representing enhancements of 5.1 times in HTC and 2.3 times in CHF than the uncoated surface. The coated surface initiate boiling earlier and maintains lower surface superheats across the entire range of heat flux compared to the uncoated surfaces. The larger number of active nucleation sites on coated surfaces contributes to improving the heat transfer rate. The coated surface also exhibits capillary wicking properties. The enhancement ratio of CHF on coated surfaces demonstrates a linear relationship with the nondimensional wicking number (Wi). In the wall jet flow boiling study, it is observed that the wall jet flow effectively enhances the boiling performance in the low heat flux nucleate boiling regimes for both coated and plain surfaces. At higher heat fluxes, the heat transfer results for different jet velocities coincide and they overlap the pool boiling results. Hence, nucleate boiling predominantly governs the heat transfer in this regime, with minimal effect of wall jet flow. However, the wall jet flow significantly delays the CHF limit, which shows a linear relationship with jet velocity.

The VM and OIVM structured surfaces exhibit better heat transfer performance compared to the plain surface with the use of the surfactant solution as the working fluid. The OIVM surface provides enhancement of 334.2% in HTC and 110.9% in CHF. The VM surface demonstrates a 101.8% increase in the HTC and a 41.8% improvement in the CHF. The plain, VM, and OIVM surfaces demonstrated improvement in HTC when tested with the surfactant solution, as compared to their performance with pure deionized water, across all levels of heat flux. However, despite this enhancement in HTC, the use of the surfactant solution results in a reduction in enhancement of CHF relative to the corresponding values observed with deionized water. This decline in CHF is primarily due to vapor bubble crowding near the heated surface at higher heat flux conditions, which obstructs effective liquid rewetting and leads to early surface dryout. The pool boiling enhancement methods proposed in the present research work are simple, cost-effective, mechanically robust and easily scalable. Therefore, they can be employed for efficient heat transfer in a wide range of industrial applications.

सार

उबालना ऊष्मीय ऊर्जा हस्तांतरण की एक अत्यधिक कुशल प्रक्रिया है जो परमाणु ऊर्जा रिएक्टर, जल आसवन, क्रायोजेनिक ईंधन भंडारण, भाप बिजली संयंत्र, प्रशीतन और वातानुकूलन और इलेक्ट्रॉनिक उपकरणों के ऊष्मीय प्रबंधन जैसे विभिन्न इंजीनियरिंग और औद्योगिक अनुप्रयोगों में व्यापक रूप से पाई जाती है। यह बहुत कम तापमान अंतर पर काफी बड़ी मात्रा में ऊष्मा स्थानांतरित करने के लिए वाष्पीकरण की गुप्त ऊष्मा का उपयोग करता है। नतीजतन, यह उल्लेखनीय रूप से उच्च ऊष्मा हस्तांतरण गुणांक (एचटीसी) प्रदान करता है, जो इसे उच्च ऊष्मा अपव्यय अनुप्रयोगों के लिए एक पसंदीदा तंत्र बनाता है। हालाँकि, उबलने में अधिकतम ऊष्मा प्रवाह महत्वपूर्ण ऊष्मा प्रवाह (एचटीसी) द्वारा सीमित होता है। एचटीसी तक पहुँचने के बाद, गर्म सतह पर वाष्प की एक परत विकसित होने लगती है, जिससे एचटीसी काफी कम हो जाता है। उबलने के प्रदर्शन में वृद्धि सीधे ऊर्जा दक्षता, पर्यावरणीय स्थिरता और जल संसाधन उपयोग में योगदान देती है। इसके अलावा, कॉम्पैक्ट, हल्के और उच्च प्रदर्शन वाले इलेक्ट्रॉनिक उपकरणों की लगातार बढ़ती मांग विश्वसनीय और कुशल संचालन सुनिश्चित करने के लिए उच्च ऊष्मा अपव्यय दरों को संभालने में सक्षम उन्नत थर्मल प्रबंधन समाधानों की मांग करती है। इसलिए, सिस्टम की दक्षता और परिचालन सीमा को एक साथ बढ़ाने के लिए एचटीसी और एचटीसी दोनों को और बढ़ाने के लिए सरल और सस्ते तरीकों की आवश्यकता है। उबलते हुए ऊष्मा हस्तांतरण को बेहतर बनाने के लिए विभिन्न सक्रिय और निष्क्रिय तरीकों की खोज की गई है। वर्तमान शोध कार्य मुख्य रूप से पूल उबलने के लिए स्केलेबल, लागत प्रभावी और आसानी से लागू होने वाली संवर्द्धन तकनीक के विकास पर केंद्रित है

इस कार्य में, दो नए माइक्रोचैनल विन्यास, यानी असममित दोहरी वी-नाली माइक्रोचैनल (वीएम) और ऑर्थोगोनली इंटरसेक्टिंग असममित दोहरी वी-नाली माइक्रोचैनल (ओआईवीएम) को पूल उबलने में वृद्धि का अध्ययन करने के लिए पेश किया गया है। संशोधित सतहों के कारण गर्मी हस्तांतरण वृद्धि एक संदर्भ सादे सतह से गर्मी हस्तांतरण दरों की तुलना करके स्थापित की जाती है। इसके अलावा, गर्मी हस्तांतरण पर पुनः प्रवेश चैनल ज्यामिति के प्रभाव की जांच करने के लिए, दो उपन्यास संरचित सतहों, अर्थात् ट्रेपेज़ॉइडल पुनः प्रवेश माइक्रोचैनल (टीआरएम) और खंडित ट्रेपेज़ॉइडल पुनः प्रवेश माइक्रोचैनल (एसटीआरएम) विकसित किए गए हैं और उबलते विशेषताओं की प्रयोगात्मक रूप से जांच की गई है। पूल उबलने में गर्मी हस्तांतरण को बढ़ाने के लिए एक स्केलेबल छिद्रपूर्ण तांबे की कोटिंग भी विकसित की गई है। गर्मी हस्तांतरण प्रदर्शन पर सतह विशेषता मापदंडों के प्रभाव की जांच की जाती है। पूल उबलने की गर्मी हस्तांतरण में सुधार करने के लिए सादे और लेपित सतहों पर एक शीर्ष-सामने वाली क्षैतिज सतह पर डूबी हुई दीवार जेट प्रवाह की भी जांच की गई है। इन अध्ययनों में, एक वायुमंडलीय दबाव पर संतृप्ति तापमान के तहत विआयनीकृत पानी का उपयोग करके प्रयोग किए गए हैं। विभिन्न ताप प्रवाह स्तरों पर बुलबुला गतिशीलता और इंटरफ़ेस आकृति विज्ञान को उच्च गति वाले कैमरे का उपयोग करके कैप्चर किया गया है और विस्तार से चर्चा की गई है। अंत में, पूल उबलने के प्रदर्शन पर सतह

संरचना और सतह योजक के संयुक्त प्रभाव का पता लगाने के लिए, ट्राइटन एक्स-100 सर्फेक्टेंट समाधान का उपयोग करके वीएम और ओआईवीएम सतह पर जांच की गई है

यह देखा गया कि गर्म सतह पर सूक्ष्म चैनल पूल उबलने में ऊष्मा स्थानांतरण में सुधार करते हैं। ओआईवीएम सतह संदर्भ समतल सतह की तुलना में अधिकतम एचटीसी में 5.3 गुना और एचटीसी में 2.4 गुना वृद्धि प्रदान करती है। इसी तरह, वीएम सतह समतल सतह की तुलना में एचटीसी में 2.2 गुना और एचटीसी में 1.7 गुना सुधार प्रदान करती है। ओआईवीएम और वीएम सतहों के साथ बढ़ी हुई ऊष्मा स्थानांतरण दर को ऊष्मा विनिमय के लिए बड़े क्षेत्र, बुलबुला आरंभ स्थलों में वृद्धि, बुलबुला गति द्वारा बढ़ावा दिया गया मैक्रोकन्वेक्शन और कुशल रीवेटिंग तंत्र के लिए जिम्मेदार ठहराया जा सकता है। टीआरएम सतह समतल सतह की तुलना में एचटीसी में 2.08 से 2.91 गुना और एचटीसी में 2.33 से 3.96 गुना वृद्धि कारक प्रदर्शित करती है। शीर्ष प्रदर्शन करने वाली एसटीआरएम सतह 4555.2 kW/m^2 का एचटीसी दिखाती है जो समतल सतह एचटीसी से 290% अधिक है। यह सतह $842.5 \text{ kW/m}^2\text{K}$ का अधिकतम एचटीसी प्रदर्शित करती है। टीआरएम सतह की तुलना में एसटीआरएम सतह के साथ बेहतर ताप स्थानांतरण प्रदर्शन यह दर्शाता है कि पृथक वाष्प उत्सर्जन और द्रव आपूर्ति मार्ग, तथा बेहतर पुनः आर्द्रिकरण विलंबित सीएचएफ और उच्च एचटीसी का मुख्य कारण हैं

लेपित सतहें बिना लेपित सतह की तुलना में बेहतर ऊष्मा स्थानांतरण प्रदर्शन प्रदान करती हैं। सबसे अच्छा प्रदर्शन करने वाली लेपित सतह $290.3 \text{ kW/m}^2\text{K}$ का एचटीसी और 2700.3 kW/m^2 का एचटीसी प्रदर्शित करती है, जो बिना लेपित सतह की तुलना में एचटीसी में 5.1 गुना और एचटीसी में 2.3 गुना वृद्धि दर्शाती है। लेपित सतह पहले उबलना शुरू करती है और बिना लेपित सतहों की तुलना में ऊष्मा प्रवाह की पूरी श्रृंखला में कम सतही अतिताप बनाए रखती है। लेपित सतहों पर सक्रिय न्यूक्लियेशन साइटों की बड़ी संख्या ऊष्मा स्थानांतरण दर को बेहतर बनाने में योगदान देती है। लेपित सतह केशिका विकिंग गुण भी प्रदर्शित करती है। लेपित सतहों पर एचटीसी का वृद्धि अनुपात गैर-आयामी विकिंग संख्या (Wi) के साथ एक रैखिक संबंध प्रदर्शित करता है। वॉल जेट प्रवाह कथन अध्ययन में, यह देखा गया है कि वॉल जेट प्रवाह लेपित और सादे सतहों दोनों के लिए कम ऊष्मा प्रवाह न्यूक्लियेट कथन शासन में कथन प्रदर्शन को प्रभावी ढंग से बढ़ाता है। उच्च तापीय प्रवाह पर, विभिन्न जेट वेगों के लिए ऊष्मा स्थानांतरण परिणाम मेल खाते हैं और वे पूल कथन परिणामों को ओवरलैप करते हैं। इसलिए, नाभिकीय कथन मुख्य रूप से इस शासन में ऊष्मा स्थानांतरण को नियंत्रित करता है, जिसमें दीवार जेट प्रवाह का न्यूनतम प्रभाव होता है। हालाँकि, दीवार जेट प्रवाह एचटीसी सीमा में काफी देरी करता है, जो जेट वेग के साथ एक रैखिक संबंध दर्शाता है

वीएम और ओआईवीएम संरचित सतहें कार्यशील तरल के रूप में सर्फेक्टेंट घोल के उपयोग के साथ सादे सतह की तुलना में बेहतर ताप हस्तांतरण प्रदर्शन प्रदर्शित करती हैं। ओआईवीएम सतह एचटीसी में 334.2% और एचटीसी में 110.9% की वृद्धि प्रदान करती है। वीएम सतह एचटीसी में 101.8% वृद्धि और एचटीसी में 41.8% सुधार प्रदर्शित करती है। सादे, वीएम, और ओआईवीएम सतहों ने ताप प्रवाह के सभी स्तरों पर शुद्ध विआयनीकृत जल के साथ उनके प्रदर्शन की तुलना में सर्फेक्टेंट घोल के साथ परीक्षण करने पर एचटीसी में सुधार प्रदर्शित किया। हालाँकि, एचटीसी में इस वृद्धि के बावजूद, सर्फेक्टेंट घोल के उपयोग से विआयनीकृत जल के साथ देखे गए संगत मानों की तुलना में एचटीसी की वृद्धि में कमी आती है वर्तमान शोध कार्य में प्रस्तावित पूल कथन वृद्धि विधियाँ सरल, लागत-प्रभावी,

यांत्रिक रूप से मजबूत और आसानी से मापनीय हैं। इसलिए, उन्हें औद्योगिक अनुप्रयोगों की एक विस्तृत श्रृंखला में कुशल ताप हस्तांतरण के लिए नियोजित किया जा सकता है

Contents

Certificate	i
Acknowledgments	ii
Abstract	iv
Contents	vii
List of Figures	xii
List of Tables	xix
Nomenclature	xxi
Chapter 1 Introduction	1
1.1. Background	1
1.2. Boiling	2
1.3. Pool boiling curve	5
1.4. Applications	9
1.5. Pool boiling enhancement techniques	10
1.5.1. Active methods	11
1.5.2. Passive methods	14
1.5.3. Compound methods	15
1.6. Motivation	16
1.7. Organization of the thesis	16
Chapter 2 Literature review	18
2.1. Introduction	18
2.2. Pool boiling on plain surface	19
2.3. Pool boiling on modified surfaces	23
2.3.1. Nanoscale structured surface	23
2.3.2. Microscale structured surface	29
2.3.3. Multiscale structured surface	44
2.3.4. Heterogeneous surfaces	48
2.4. Pool boiling with modified fluids	52
2.4.1. Nanofluids	53
2.4.2. Surfactants	55

2.4.3.	Ionic liquids	57
2.4.4.	Hybrid additives	59
2.5.	Submerged boiling with jet flow	60
2.6.	Conclusions from review of literature and research gaps	63
2.7.	Objectives of present research work	65
Chapter 3	Experimental methodology	66
3.1.	Introduction	66
3.2.	Pool boiling experimental facility	66
3.3.	Wall jet flow boiling experimental facility	69
3.4.	Main heater unit	70
3.5.	Test surface preparation and characteristics	73
3.6.	Test fluids	74
3.7.	Measurement and instrumentation	74
3.8.	Experimental procedure for pool boiling experiments	76
3.9.	Experimental procedure for wall jet flow boiling experiments	78
3.10.	Data reduction	79
3.11.	Bubble dynamics parameter estimation	82
3.12.	Uncertainty analysis	84
Chapter 4	Pool boiling on an asymmetric dual V-groove microchannel structured surface	86
4.1.	Introduction	86
4.2.	Main heater unit and test surfaces	86
4.3.	Results and discussions	88
4.3.1.	Verification of experimental facility	89
4.3.2.	Pool boiling performance of plain, VM and OIVM surfaces	91
4.3.3.	Effect of area enhancement	98
4.3.4.	Bubble dynamics and heat transfer mechanisms	101
4.3.5.	Comparison with state-of-the-art	107
4.4.	Summary	111

Chapter 5 Pool boiling on trapezoidal reentrant microchannel structured surfaces	114
5.1. Introduction	114
5.2. Heater unit and test surfaces	114
5.3. Results and discussions	119
5.3.1. Reliability test	119
5.3.2. Heat transfer characteristics of the plain, RM-1 and TRM surfaces	122
5.3.3. High-speed visualization of bubble dynamics on the plain, RM-1 and TRM surfaces	128
5.3.4. Heat transfer characteristics of STRM surfaces	132
5.3.5. High-speed visualization of bubble dynamics on the STRM surfaces	136
5.3.6. Comparison of pool boiling performance in different microchannel configurations	140
5.3.7. CHF enhancement mechanisms	145
5.3.8. Bubble dynamics parameters over different surfaces	148
5.3.9. Comparison of pool boiling performance with the enhanced surfaces available in literature	152
5.4. Summary	156
Chapter 6 Pool boiling on thermally sprayed porous copper coated surfaces	159
6.1. Introduction	159
6.2. Surface coating fabrication method	159
6.3. Results and discussions	161
6.3.1. Surface characterization of thermal spray coated test surfaces	162
6.3.1.1. Surface morphology, roughness and porosity	162
6.3.1.2. Wettability and wickability characteristics	169
6.3.2. Pool boiling heat transfer results	172
6.3.2.1. Heat transfer performance comparison of different surfaces	172
6.3.2.2. Bubble dynamics analysis	176
6.3.2.3. Effect of surface characteristics on CHF	181
6.3.2.4. Coating stability test	185
6.3.2.5. Comparison with existing modified/coated surfaces	186
6.4. Summary	189

Chapter 7 Effect of wall jet flow on boiling heat transfer over a plain and coated surfaces	192
7.1. Introduction	192
7.2. Test surfaces and flow parameters	192
7.3. Results and discussions	195
7.3.1. Wall jet flow boiling on a plain copper surface	195
7.3.2. Effect of nozzle to heater surface spacing	201
7.3.3. Two-phase flow morphology evolution on plain surface	202
7.3.4. Wall jet flow boiling on a coated copper surface	204
7.3.5. Effect of surface characteristics	208
7.3.6. Two-phase flow morphology evolution on coated surface	210
7.3.7. Effect of system parameters and surface characteristics on the CHF	212
7.4. Summary	214
Chapter 8 Pool boiling on microchannel structured surfaces using a nonionic surfactant solution	217
8.1. Introduction	217
8.2. Test surfaces and boiling fluid	217
8.3. Results and Discussion	218
8.3.1. Repeatability test	218
8.3.2. Heat transfer results of plain, VM and OIVM surfaces	219
8.3.3. Comparison of Triton X-100 solution heat transfer results with the pure deionized water heat transfer results	223
8.3.4. Comparison of boiling behaviour	226
8.4. Summary	230
Chapter 9 Conclusion and recommendations for future research	231
9.1. Introduction	231
9.2. Major conclusions	232
9.3. Recommendations for future research	235
References	237
Appendix A	257

Appendix B	262
Appendix C	266
Appendix D	269
Appendix E	270
List of publications	271
Bio-Data	272

List of Figures

Figure 1.1	Comparison of HTC during convective heat transfer with various working fluids.	2
Figure 1.2	Schematic diagram of pool boiling and flow boiling configurations.	4
Figure 1.3	Comparison of boiling phenomena in saturated and subcooled bulk conditions.	4
Figure 1.4	Pool boiling curve of water at atmospheric pressure.	6
Figure 1.5	Schematic representation of different boiling regimes.	7
Figure 1.6	A schematic diagram which illustrating the different stages involved in the bubble ebullition cycle during heterogeneous nucleation.	9
Figure 1.7	Various boiling applications: (a) Nuclear power reactors (b) Water distillation (c) Cryogenic fuel storage (d) Steam power plant (e) Refrigeration and air conditioning (f) Electronic cooling.	10
Figure 1.8	Classification of various boiling heat transfer enhancement methods	11
Figure 2.1	Schematic illustration of different forces acting on vapour bubble interface according to Kandlikar's approach [54].	22
Figure 2.2	SEM images of various nanostructured surfaces developed for boiling applications (adapted from respective articles).	25
Figure 2.3	Representative SEM images of various nanostructured surfaces developed in literature (adapted from respective articles).	28
Figure 2.4	SEM images of various rough surfaces developed in literature (adapted from respective articles).	31
Figure 2.5	Variis structured surfaces developed in the literature for boiling enhancement (adapted from respective article).	38
Figure 2.6	Various coated surfaces developed in literature for the enhancement of boiling performance (adapted from respective article).	42
Figure 2.7	Various multiscale structured surface developed in literature (adapted from respective article)	48
Figure 2.8	Various heterogeneous surfaces developed for pool boiling enhancement (adapted from respective article).	52
Figure 3.1	Schematic diagram of pool boiling test setup.	67
Figure 3.2	Photograph of the boiling test facility.	68

Figure 3.3	Schematic of wall jet flow boiling experimental facility.	69
Figure 3.4	Schematic diagram of main heater unit.	70
Figure 3.5	Isometric representation of the copper block. (all dimensions are in mm).	72
Figure 3.6	The schematic of experimental scheme used wickability testing.	73
Figure 3.7	Spatial variation of temperature along centre line of copper module below boiling surface.	81
Figure 3.8	Representative image to show the estimation of bubble departure diameter.	83
Figure 4.1	Different configurations of microchannel surface (a) VM (b) OIVM.	87
Figure 4.2	Side view of the VM and OIVM surfaces.	88
Figure 4.3	Comparison of the pool boiling curve and CHF value on plain surface with results reported in the literature.	90
Figure 4.4	Repeatability of boiling results on plain surface.	91
Figure 4.5	Pool boiling curves of different surfaces using projected area.	93
Figure 4.6	Evolution of bubble ebullition cycle on VM structured surface at a heat flux of $\approx 70 \text{ kW/m}^2$.	95
Figure 4.7	Variation of HTC with heat flux for different surfaces using projected area.	97
Figure 4.8	Pool boiling curves of different surfaces using true area of heated surface.	99
Figure 4.9	Variation of HTC with heat flux for different surfaces using true area of heated surface.	100
Figure 4.10	Visualization of bubble behavior at heat flux of $\approx 120 \text{ kW/m}^2$ (a) plain, (b) VM and (c) OIVM.	102
Figure 4.11	Visualization of bubble behavior at heat flux of $\approx 250 \text{ kW/m}^2$ (a) plain, (b) VM and (c) OIVM.	103
Figure 4.12	Mechanism of liquid-vapour pathways separation on an asymmetric dual V-groove microchannel surface.	104

Figure 4.13	Visualization of bubble behavior at the heat flux of $\approx 1750 \text{ kW/m}^2$ (a) VM and (b) OIVM.	105
Figure 4.14	Schematic diagram of boiling phenomenon over OIVM surface.	106
Figure 4.15	Comparison of boiling curves with existing modified surfaces.	108
Figure 4.16	Comparison of HTC with existing modified surfaces.	110
Figure 5.1	Isometric view of the developed STRM surface.	115
Figure 5.2	The SEM images of developed structured surfaces: (a) side and top view of four microgrooves (b) magnified view of microgroove bottom (c) magnified view of microgroove top (d) side view of secondary rectangular microgroove.	116
Figure 5.3	Heat transfer results obtained in the present study with the reference plain surface and those available in literature.	120
Figure 5.4	The repeatability test for the heat transfer results of the plain surface.	121
Figure 5.5	Comparison of the pool boiling curves of the plain, RM-1, TRM-0.25, TRM-0.5 and TRM-0.75 surfaces with water at the saturated condition using the projected area.	123
Figure 5.6	Comparison of the HTC for plain, RM-1, TRM-0.25, TRM-0.5 and TRM-0.75 surfaces.	126
Figure 5.7	Boiling phenomenon images at heat flux of $\approx 200 \text{ kW/m}^2$ (a) Plain surface, (b) RM-1 surface and (c) TRM-0.5 surface.	129
Figure 5.8	Boiling phenomenon images at heat flux of $\approx 450 \text{ kW/m}^2$ (a) Plain surface, (b) RM-1 surface and (c) TRM-0.5 surface.	131
Figure 5.9	Boiling phenomenon images at heat flux of $\approx 850 \text{ kW/m}^2$ (a) Plain surface, (b) RM-1 surface and (c) TRM-0.5 surface.	132
Figure 5.10	Comparison of pool boiling curves for various STRM surfaces.	134
Figure 5.11	HTC comparison for various STRM surfaces in the entire range of heat flux.	135

Figure 5.12	Boiling phenomenon images at heat flux of $\approx 250 \text{ Kw/m}^2$ (a) SRTM-1 surface, (b) SRTM-2 surface, (c) SRTM-3 surface and (d) STRM-4 surface.	136
Figure 5.13	Boiling phenomenon images at heat flux of $\approx 500 \text{ kW/m}^2$ (a) SRTM-1 surface, (b) SRTM-2 surface, (c) SRTM-3 surface and (d) STRM-4 surface.	138
Figure 5.14	Schematic diagram of bubble dynamics on STRM-3 surface.	140
Figure 5.15	Comparison of pool boiling curves for plain, RM-1, TRM-0.5 and STRM-3 surfaces with water at saturated condition using the projected area.	141
Figure 5.16	HTC comparison for plain, RM-1, TRM-0.5 and STRM-3 surfaces of heat flux.	143
Figure 5.17	Boiling curves of TRM-0.5 and STRM-3 surfaces obtained on different days.	145
Figure 5.18	CHF enhancement ratio as a function of the wicking number (Wi) for different surfaces.	148
Figure 5.19	Comparison of HTC and CHF enhancement ratio of present best-performing (STRM-3) surface with other enhanced surfaces available in literature.	153
Figure 6.1	Schematic illustration of atmospheric plasma thermal spray coating method.	160
Figure 6.2	FESEM image of copper powder.	162
Figure 6.3	FESEM image of the reference plain copper surface.	163
Figure 6.4	FESEM images of fabricated porous surfaces show the surface morphology of different coated surfaces (a) C-1, (b) C-2, (c) C-3 and (d) C-4.	164
Figure 6.5	FESEM images of different coatings cross-section (a) C-1, (b) C-2, (c) C-3 and (d) C-4.	165
Figure 6.6	X-ray diffraction patterns of feedstock copper powder and coated surfaces.	167

Figure 6.7	3D optical profilometry profiles of different surfaces (a) plain surface, (b) C-1, (c) C-2, (d) C-3, (e) C-4.	168
Figure 6.8	Schematic diagram of the wicking flux measurement scheme.	170
Figure 6.9	Liquid volume absorbed by different coated surfaces as a function of time during wickability tests.	171
Figure 6.10	Comparison of the boiling curves of different surfaces.	173
Figure 6.11	HTC variation with heat flux for different surfaces.	175
Figure 6.12	High-speed images of boiling phenomena on the different surfaces at various heat fluxes.	178
Figure 6.13	Variation in the ratio of CHF with the wickability.	183
Figure 6.14	Schematic of the boiling phenomenon on the coated surface.	184
Figure 6.15	Coating stability testing for C-4 surfaces over a period of 9 days.	185
Figure 6.16	The boiling curves of C-4 and other modified surfaces.	186
Figure 6.17	Comparison of HTC with other modified surface results.	187
Figure 7.1	Comparison of boiling curves obtained using different jet velocities for wall jet flow boiling configuration with pool boiling curve over plain surface at S/D_h of 4.	196
Figure 7.2	Comparison of HTC in wall jet flow and pool boiling configurations at various heat flux levels for plain surface at S/D_h of 4.	199
Figure 7.3	Comparison of the boiling curves obtained with the plain surface for wall jet velocity of 2 m/s at S/D_h of 4 and 8.	202
Figure 7.4	Saturated wall jet flow boiling morphology visualization over plain surface at different heat flux levels for $V_{wj} = 2$ m/s with $S/D_h = 4$ configuration.	203

Figure 7.5	Comparison of heat transfer results obtained using different jet velocities for wall jet flow boiling configuration with pool boiling data over coated surface at S/D_h of 4.	205
Figure 7.6	Comparison of HTC in wall jet flow and pool boiling configurations at various heat flux levels for coated surface at S/D_h of 4.	207
Figure 7.7	Comparison of the plain and coated surface boiling curves at an S/D_h ratio of 4 under jet velocity of 2 m/s.	209
Figure 7.8	Saturated wall jet flow boiling morphology visualization over coated surface at different heat flux levels for $V_{wj} = 2$ m/s with $S/D_h = 4$ configuration.	212
Figure 7.9	Variation in the CHF as a function of jet velocity.	213
Figure 8.1	Pool boiling curves of surfactant solution with the plain surface during three different experimental runs.	219
Figure 8.2	Comparison of heat transfer performance of different surface with the Triton X-100 solution.	220
Figure 8.3	Comparison of HTC obtained with the plain, VM and OIVM surfaces using Triton X-100 surfactant solution.	221
Figure 8.4	Comparison of Triton X-100 and pure deionized water boiling curves on plain, VM and OIVM surfaces.	223
Figure 8.5	Comparison of HTC enhancement factor for plain, VM and OIVM surface with the surfactant solution in different heat flux regimes.	225
Figure 8.6	Boiling phenomenon at ≈ 120 kW/m ² on the different test surfaces (a) plain (b) VM and (c) OIVM using deionized water and (d) plain (e) VM and (f) OIVM using Triton X-100 solution.	227

Figure 8.7 Boiling phenomenon at near CHF on the different test surfaces (a) 229
plain (b) VM and (c) OIVM using deionized water and (d) plain
(e) VM and (f) OIVM using Triton X-100 solution.

List of Tables

Table 3.1	Properties of the surfactant used.	74
Table 3.2	Detail of equipment and sensors used in the boiling facility.	75
Table 4.1	Microchannel dimensions in the modified surfaces	88
Table 4.2	Comparison of heat transfer results using the projected area of boiling surface.	98
Table 4.3	Comparison of heat transfer results based on the actual area of heated surface.	100
Table 4.4	Comparison of OIVM surface boiling performance with existing microscale modified surfaces.	111
Table 5.1	The details of geometrical parameters of the developed test surfaces.	117
Table 5.2	Comparison of the plain and modified surfaces heat transfer results.	125
Table 5.3	Comparison of heat transfer performance with different STRM surfaces.	135
Table 5.4	Comparison of heat transfer performance evaluated using projected area.	142
Table 5.5	Heat transfer results calculated utilizing actual surface area.	143
Table 5.6	Bubble departure diameter and departure frequency for different surfaces at the at the heat flux of $\approx 100 \text{ kW/m}^2$.	150
Table 5.7	Maximum HTC and CHF achieved with the present STRM-3 surface and the different modified surfaces available in literature.	155
Table 6.1	Atmospheric plasma thermal spray coating system operating parameters.	161
Table 6.2	Elemental analysis of different coatings.	165
Table 6.3	Roughness, porosity and coating thickness of different coatings.	168
Table 6.4	HTC and CHF results for different surfaces.	176
Table 6.5	Comparison of measured bubble dynamics parameters with the existing correlations at the heat flux of $\approx 100 \text{ kW/m}^2$.	180

Table 6.6	Wickability test results.	183
Table 6.7	Comparison of the best-performing surface (C-4) maximum HTC and CHF with other modified surfaces available in literature.	188
Table 7.1	Surface characteristics of plain and coated boiling test surfaces.	194
Table 7.2	Summary of flow and geometrical parameters used in the wall jet flow boiling tests.	195
Table 7.3	CHF and Maximum HTC values for the plain surface.	200
Table 7.4	Maximum HTC and CHF obtained with the coated surface.	208
Table 8.1	Comparison of heat transfer results obtained with different surface using Triton X-100 solution.	222
Table 8.2	Comparison of Max HTC and CHF with the plain surface and deionized water results.	226

Nomenclature

a	channel opening (m)
A	surface area (m ²)
A_w	wetted area (m ²)
b	channel base width (m)
c_p	specific heat at constant pressure (J/kgK)
D, d	depth of channel (m)
d_b	bubble departure diameter (m)
D_h	hydraulic diameter (m)
f_b	bubble departure frequency (/s)
g	Acceleration due to gravity (m/s ²)
h	heat transfer coefficient (W/m ² K)
h_{fg}	latent heat of vaporization (J/kg)
I	electrical current (A)
k	thermal conductivity (W/mK)
N	number of channels
P, p	pitch of channels (m)
Pr	Prandtl number $\left(\frac{\mu c_p}{k}\right)$
q''	heat flux (W/m ²)
Re	Reynold number $\left(\frac{\rho V L_c}{\mu}\right)$
S	distance between nozzle and heated surface (m)
t	time (s)
t_g	growth time (s)
t_w	waiting time (s)
T	temperature (K)
U	uncertainty
V	voltage (V)
V_{w_j}	wall jet velocity (m/s)
V_0''	initial wicked flux (m/s)
W	width of channel (m)
Wi	nondimensional wicking number
X	distance (m)

Greek symbols

ΔT	wall superheat (K)
ΔX	spacing between two adjacent thermocouples (m)
φ	inclination angle ($^{\circ}$)
μ	dynamic viscosity (Ns/m ²)
ρ	density (kg/m ³)
σ	surface tension (N/m)
θ	contact angle ($^{\circ}$)

Subscripts

<i>Cu</i>	copper
<i>f</i>	liquid
<i>g</i>	vapour
<i>in</i>	input
<i>sat</i>	saturation
<i>sub</i>	subcooling
<i>sup</i>	superheat
<i>w</i>	wall
<i>wj</i>	wall jet

Abbreviations

CHF	Critical heat flux
CMC	Critical micelle concentration
EDS	Energy dispersive X-ray spectroscopy
FESEM	Field emission scanning electron microscope
HTC	Heat transfer coefficient
MHU	Main heating unit
OIVM	Orthogonally intersecting asymmetric dual V-groove microchannels surface
RM	Rectangular microchannels surface
SEM	Scanning electron microscope
STRM	Segmented trapezoidal reentrant microchannels surface
TRM	Trapezoidal reentrant microchannels surface
VM	Asymmetric dual V-groove microchannels surface
WEDM	Wire electric discharge machining
XRD	X-ray diffraction